

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TOYOTA MOTOR ENGINEERING & MANUFACTURING NORTH AMERICA, INC.	01/21/2015
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Property Type	Number
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Total Attachments: 1	
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ASSIGNMENT

WHEREAS, **Toyota Motor Engineering & Manufacturing North America, Inc.** a corporation of the State of Kentucky, with a place of business at 25 Atlantic Avenue, Erlanger, KY 41018 (hereinafter referred to as Assignor), is the sole owner of the entire right, title and interest in and to the following United States Letters Patent No. 8,921,989 entitled **Power Electronics Modules with Solder Layers Having Reduced Thermal Stress** (hereinafter referred to as "Letters Patent").

WHEREAS, **Toyota Jidosha Kabushiki Kaisha**, a business of Japan, with a place of business at 1, Toyota-cho, Toyota-shi, Aichi-ken 471-8571, Japan (hereinafter referred to as Assignee) is desirous of acquiring the entire right, title and interest in and to the aforesaid Letters Patent, and the inventions therein described;

NOW, THEREFORE, for good and valuable consideration, receipt whereof is hereby acknowledged, Assignor hereby sells, assigns and transfers unto said Assignee, its successors and assigns, the entire right, title and interest in and to Letters patent, and the inventions therein disclosed, and any improvements thereon, the same to be held and enjoyed by the said Assignee for its own use and benefit, and for the use and benefit of its successors, assigns or other legal representatives to the full end of the term for which said Letters Patent has been granted or may be granted, as fully and entirely as the same would have been held and enjoyed by said Assignor, if this assignment and sale had not been made; together with all claims for damages by reason of past infringement of said Letters Patent, with the right to sue for, and collect the same for its own use and benefit, and for the use and benefit of its successors, assigns and other legal representatives.

**Toyota Motor Engineering &
Manufacturing North America, Inc.**

Date: 4/21/2015

Name: [Signature]

Title: IP Counsel